

Title (en)  
SEMICONDUCTOR CHIP ENCAPSULATION METHOD, DEVICE PRODUCED BY THIS METHOD AND ITS APPLICATION TO THREE DIMENSIONAL CHIP INTERCONNECTION.

Title (de)  
UNHÜLLUNGSVERFAHREN FÜR HALBLEITERCHIPS, DARAUS GEWONNENE TEILE UND VERWENDUNG FÜR DIE DREIDIMENSIONALE VERDRAHTUNG.

Title (fr)  
PROCEDE D'ENCAPSULATION DE PASTILLES SEMI-CONDUCTRICES, DISPOSITIF OBTENU PAR CE PROCEDE ET APPLICATION A L'INTERCONNEXION DE PASTILLES EN TROIS DIMENSIONS.

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Application  
**EP 94913654 A 19940415**

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Abstract (en)  
[origin: WO9425987A1] According to the method of the invention, conductive leads are directly wired onto a semiconductor wafer carrying a large number of chips, the wafer is bonded to a resilient film and cut to separate each chip, after which the film is stretched to space the chips; the totality of the chips and leads are then held in an insulating material such as a polymerizable resin, and, after polishing, metal plating is applied over the leads to connect them to the sides of the chips; the assembly is then cut in order to separate the chips.

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Citation (search report)  
See references of WO 9425987A1

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